

(12) INTERNATIONAL APPLICATION PUBLISHED UNDER THE PATENT COOPERATION TREATY (PCT)

(19) World Intellectual Property
Organization
International Bureau



(43) International Publication Date
21 October 2004 (21.10.2004)

PCT

(10) International Publication Number
WO 2004/090981 A1

(51) International Patent Classification⁷: H01L 23/64, 23/498 [DE/DE]; c/o Philips Intellectual Property & Standards GmbH, Weisshausstr. 2, 52066 Aachen (DE).

(21) International Application Number: PCT/IB2004/000992

(22) International Filing Date: 31 March 2004 (31.03.2004)

(25) Filing Language: English

(26) Publication Language: English

(30) Priority Data: 03100921.0 7 April 2003 (07.04.2003) EP

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(81) Designated States (unless otherwise indicated, for every kind of national protection available): AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BW, BY, BZ, CA, CH, CN, CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD, MG, MK, MN, MW, MX, MZ, NA, NI, NO, NZ, OM, PG, PH, PL, PT, RO, RU, SC, SD, SE, SG, SK, SL, SY, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, YU, ZA, ZM, ZW.

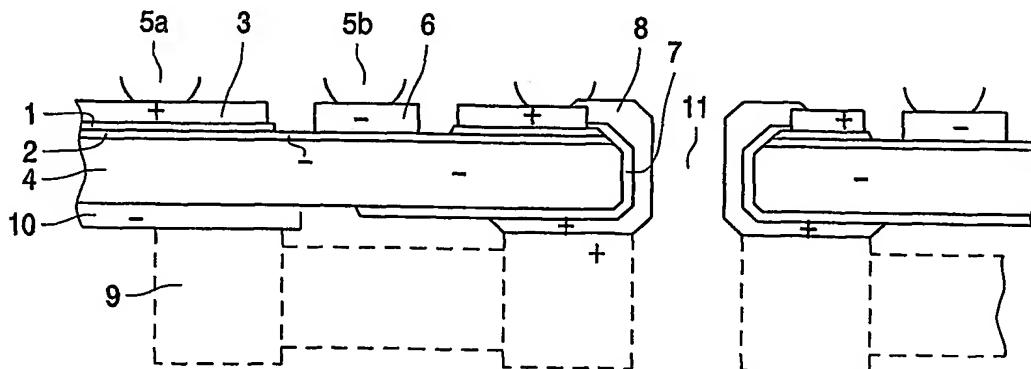
(84) Designated States (unless otherwise indicated, for every kind of regional protection available): ARIPO (BW, GH, GM, KE, LS, MW, MZ, SD, SL, SZ, TZ, UG, ZM, ZW), Eurasian (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European (AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HU, IE, IT, LU, MC, NL, PL, PT, RO, SE, SI, SK, TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG).

Published:

- with international search report
- before the expiration of the time limit for amending the claims and to be republished in the event of receipt of amendments

[Continued on next page]

(54) Title: ELECTRONIC PACKAGING STRUCTURE WITH INTEGRATED DISTRIBUTED DECOUPLING CAPACITORS



(57) Abstract: An electronic packaging structure, comprising a substrate; a first electrode layer on a first side of said substrate; dielectric material arranged in a preselected pattern on said first electrode layer; and a second electrode layer forming a plurality of second electrodes which are arranged on said preselected pattern of dielectric material to form a distributed capacitive structure together with said first electrode layer, is characterized in that a second decoupling capacitor stage is arranged on a second side of said substrate opposite said first side and is electrically connected to said distributed capacitive structure, said second decoupling stage having a capacity higher than that of said distributed capacitive structure.



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